

## Soldered SAM data sheet SAM- $\lambda$ -A-25.0s

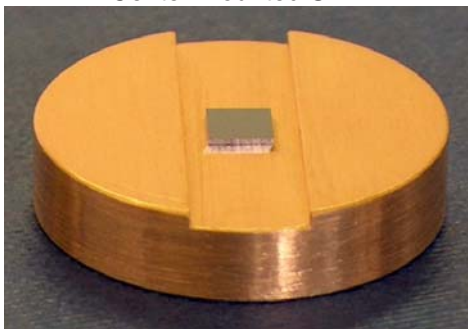
GaAs chip area	standard:	4mm x 4mm
	optional:	other dimensions on request
Chip thickness	standard:	400 $\mu$ m
	optional:	150 $\mu$ m

Front side protection            the SAM is protected with a dielectric front layer.

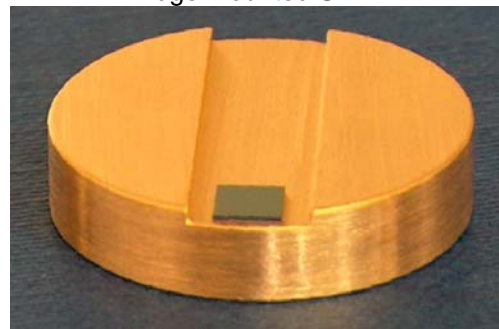
The SAM chip is soldered on a gold plated Cu-cylinder with 25.0 mm  $\varnothing$  using a Sn/Bi solder. The solder provides a low thermal resistance between the SAM and the mount.

- The **standard** position of the SAM is at the center of the mount.
- **Optional** the SAM can be soldered on the edge of the mount without extra charges.

Center mounted SAM



Edge mounted SAM



### Mount

Cu-cylinder,  $\varnothing = 25.0$  mm  
l = 6.0 mm

